



Features

- \bullet 5.0mm X 5.0mm X 1.2mm SMD LED
- Zener diode provided for ESD protection
- IR-reflow compatible
- Standard Package: 500 pcs/Reel
- MSL (Moisture Sensitivity Level): 3
- RoHS compliant.







ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES

Package Schematics 5.4[0.213] 64.410.1731 1.2[0.047] 5[0.197] 0.4[0.016] 3 4 5[0.197] 5 2 6 1 **POLARITY** MARK CHIP 0.8[0.031] 1[0.039] 1_{Ø1.8}[0.071] 6 4.2[0.165] 1[0.039]5 2 3 Slug

Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
- 3. Specifications are subject to change without notice.
- 4. The device has a single mounting surface. The device must be mounted according to the specifications.

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XDSB6195 V4-Z Layout: Maggie L.



Handling Precautions

Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force.

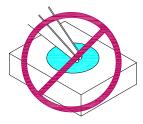
As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools.

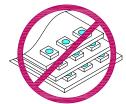


2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.

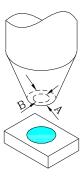




3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



- $4.1. \ The inner diameter of the \ SMD \ pickup \ nozzle \ should \ not \ exceed \ the \ size \ of \ the \ LED \ to \ prevent \ air \ leaks.$
- 4.2. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
- 4.3. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.

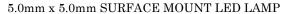


5. As silicone encapsulation is permeable to gases, some corrosive substances such as H_2S might corrode silver plating of leadframe. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.

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Part Number: XZCB14X146S





Selection Guide

Part Number	Dice	Lens-color	Luminous Intensity CIE127-2007* $(I_F=350 \mathrm{mA})$ [2] cd		CIE12' (I _F =350	ous Flux 7-2007* mA)*[2] m	Viewing Angle 2 0 1/2 [1]
			Min.	Typ.	Min.	Тур.	
XZCB14X146S	Blue (InGaN)	Water Clear	4.2*	5.49*	14*	19.7*	120°

Notes:

- 1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value. 2. Luminous intensity / luminous flux: +/-15%,*LEDs are binned according to their luminous flux.

Absolute Maximum Ratings at Ta=25°C

Parameter	Symbol	Value	Unit	
Power Dissipation	PD	1.33	W	
DC Forward Current [1]	IF	350	mA	
Peak Forward Current [2]	IFP	600	mA	
Reverse Voltage	VR	5	V	
Junction temperature	TJ	110	°C	
Operating Temperature	Top	-40 To +100	°C	
Storage Temperature	Tstg	-40 To +110	°C	
Thermal Resistance [1]	Rth j-a	23.8	°C/W	
Electrostatic Discharge Threshold (HBM)		8000	V	

- 1. Results from mounting on metal core PCB, mounted on pc board-metal core PCB is recommend for lowest thermal resistance.
- 2. 1/10 Duty Cycle, 0.1ms Pulse Width.

Electrical / Optical Characteristics at Ta=25°C

Parameter	Symbol	Value	Unit	
Wavelength at peak emission IF = 350mA CIE127-2007* [Typ.]	λpeak	455*	nm	
Dominant Wavelength IF = 350mA CIE127-2007* [Typ.]	λdom [1]	460*	nm	
Spectral bandwidth at 50% Φ REL MAX IF = 350mA [Typ.]	$ riangle \lambda$	25	nm	
Forward Voltage IF=350mA [Typ.]	VI 101	3.3	77	
Forward Voltage IF=350mA [Max.]	V _F [2]	3.8	V	
Allowable Reverse Current [Max.]	IR	85	mA	
Temperature coefficient of λ peak IF = 350mA, - 10°C \leq T \leq 100°C [Typ.]	ТС\peak	0.2	nm/°C	
Temperature coefficient of λ dom IF = 350mA, - 10°C \leq T \leq 100°C [Typ.]	TCλdom	0.1	nm/°C	
Temperature coefficient of V _F I _F = 350mA, - 10°C ≤ T≤ 100°C [Typ.]	TCv	-2.3	mV/°C	

Notes:

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^{*} Luminous Intensity/Luminous Flux value is in accordance with CIE127-2007 standards.

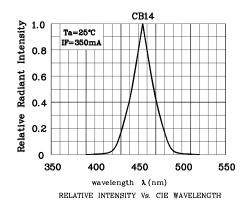
^{1.} Wavelength: + / -1 nm.

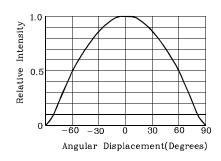
^{2.} Forward Voltage: +/-0.1V.

^{*}wavelength value is in accordance with CIE127-2007 standards.

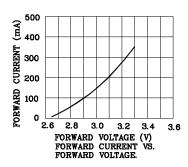


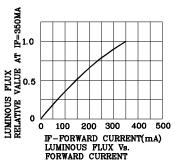


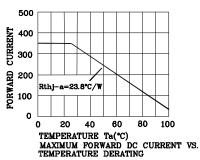


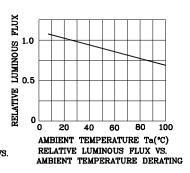


♦ CB14



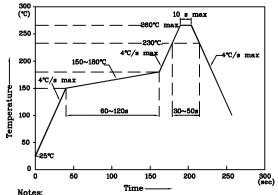






LED is recommended for reflow soldering and soldering profile is shown below.

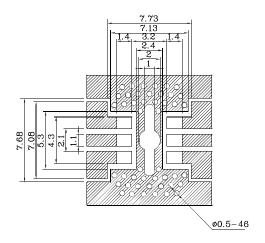
Reflow Soldering Profile for SMD Products (Pb-Free Components)

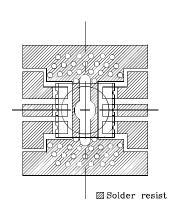


- 1. Maximum soldering temperature should not exceed 260°C
- 2. Recommended reflow temperature: 145°C-260°C
- 3. Do not put stress to the epoxy resin during high temperatures conditions

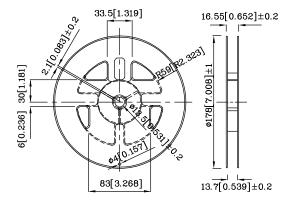


❖ Recommended Soldering Pattern (Units:mm; Tolerance: ± 0.1)

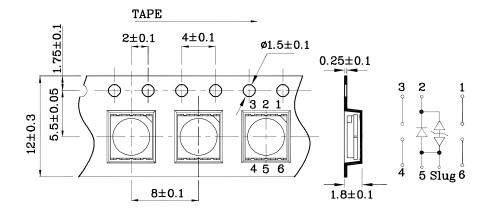




❖ Reel Dimension



❖ Tape Specification (Units:mm)



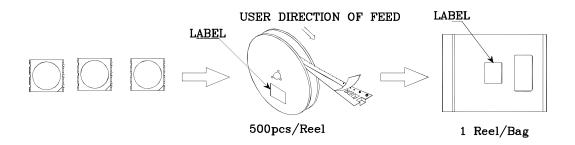
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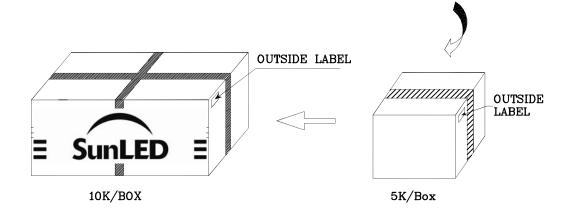
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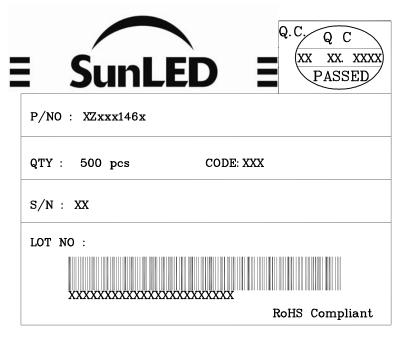


PACKING & LABEL SPECIFICATIONS

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